## **DECLARATION AND POWER OF ATTORNEY**

As a below named inventor	, I hereby declare that:		
My residence, post office a	nd citizenship are as stated	d below next to my name,	
plural names are listed belo	ow) of the subject matter c DISPLAYING THRI	only one name is listed below) or a laimed and for which a patent is so EE-DIMENSIONAL IMAG as Application Serial	E, the specification of which
	amended on	(if appli	cable)
specification, including the	I hereby state that I claims, as amended by an	have reviewed and understand by amendment referred to above.	the contents of the above identified
in accordance with Title 37,	I acknowledge the duty Code of Federal Regulation	to disclose information which is knows, Section 1.56(a).	own to me to be material to patentability
country other than the Uni	unventor's certificate, or lited States of America, list aventor's certificate, or of	365(a) of any PCT international aped below and have also identified.	. 119(a)-(d) or 365 (b) of any foreign pplication which designated at least one below, by checking the box, any foreign a having a filing date before that of the
Prior Foreign Application(s): Number		Country	Foreign Filing Date Month/Day/Year
2003-13084	)	Korea	March 03, 2003
	<del></del>		
I hereby claim the benefit us	nder 35 U.S.C. 119(e) of an	y United States provisional applicat	ion(s) listed below.
Application Number(s):		Filing Date (Month/Day/Year)	
designating the United State not disclosed in the prior Ur	inder 35 U.S.C. 120 of any	United States application(s), or 36	5(c) of any PCT international application
available between the filing of Prior U. S. Applic or PCT Parent No.	nited States or PCT internary to disclose information date of the prior application cation	and, insofar as the subject matter of	of each of the claims of this application is ovided by the first paragraph of 35 U.S.C. s defined in 37 CFR 1.56 which became
Prior U. S. Applic	nited States or PCT internation to disclose information date of the prior application cation  Tiling	and, insofar as the subject matter of tional application in the manner pro- which is material to patentability at a and the national or PCT internation Date (Month/Day/Year)	of each of the claims of this application is ovided by the first paragraph of 35 U.S.C. is defined in 37 CFR 1.56 which became onal filing date of this application.  Parent Patent Number

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on infomation and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or ageot(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Carol L. Druzbick, Registration No. 40,287; Anthony H. Nourse, Registration No. 46,121; Laura L. Lee, Registration No. 48,752; Rene A. Vazquez, Registration No. 38,647; Donald R. McPhail, Registration No. 35,811; Timothy M. Speer, Registration No. 47,355; Samuel W. Nitros, Registration No. 39,318; Mark R. Buscher, Registration No. 35,006; and Daniel H. Shext, Registration No. 46,425, all of

## P. O. Box 221200 Chantilly, Virginia 20153-1200

with full power of substitution and tevocation, to prosecute this application and to transact all business in the Patent and Tendemark Office connected therewith, and all future correspondence should be addressed to them. Full name of sole or first inventor Tae Soo PARK Inventor's signature: Date: 100 Mailing Address: Kolong APT. 105-1007, Bangl-dong, Songpa-gu, Scoul, Republic of Korea Cirizenship: Korean Residence Address (only if different from mailing address): Full name of sole or first inventor: Inventor's signature: Date: Mailing Address: Citizenship: Residence Address (only if different from mailing address): Full name of sole or first inventor. Inventor's signature: Date: Mailing Address: Citizenship: Residence Address (only if different from mailing address): Full name of sole or first inventor: Inventor's signature: Date: Mailing Address: Citizenship: Residence Address (only if different from mailing address):

## BEST AVAILABLE COPY